

Electronic Patent Application Fee Transmittal

Application Number:	10538306			
Filing Date:	09-Jun-2005			
Title of Invention:	Copper alloy for wiring, semiconductor device, method for forming wiring and method for manufacturing semiconductor device			
First Named Inventor/Applicant Name:	Makoto Ueki			
Filer:	Bruce Elliot Kramer/derrick hill			
Attorney Docket Number:	Q88465			

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Extension - 3 months with \$130 paid	1253	1	980	980
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				1790